



## LEAD FRAME SPECIFICATION REVIEW APPROVE FORM

SPEC#: XXX

FOR LEAD FRAME TYPE: ☒ Etch type ☐ Stamp type

Page : 01/04

LF MATERIAL : C7025 HH

Tape MATERIAL ☐ R970 ☐ R722 ☒ NONE ☐ Other \_\_\_\_\_

VQFP 128L 6.000SQ MTX3 PKG:14X14 ILP:0.177

SUPPLIER: SET		CODE:	
SUPPLIER PART NUMBER:		rev. Orig.	
ISSUE DATE:			
RECEIVE FILE NAME	INNER CAD FILE: A12470 REV.0	STRIP CAD FILE : AAB02611 REV.0	Others:
<b><u>SUPPLIER RESPONSE:</u></b>			
<input type="checkbox"/> DRAWING AND ASSOCIATED DOCUMENTS HAVE RECEIVED AFTER ENGINEERING REVIEW AND WITHOUT ANY MANUFACTURING ISSUE NO DEVIATIONS ARE REQUIRED OR REQUESTED.			
<input checked="" type="checkbox"/> CANNOT MEET SPECIFIED CRITERIA – AS FOLLOWS (USE CONTINUATION SHEET IF NEEDED):			

A. SPECIFICATION CHANGE				
Approve Or Rejected	ITEM	ASE SPECIFICATION	SUPPLIERS NEEDED SPEC.	Date
<input checked="" type="checkbox"/> APP. <input type="checkbox"/> REJ.	Flat area of lead tip (measure at 0.254)	80% of nominal lead width	Min 0.071mm	1 JUN 2010
<input checked="" type="checkbox"/> APP. <input type="checkbox"/> REJ.	Lead position	+/-0.030	+/-0.050	1 JUN 2010
<input checked="" type="checkbox"/> APP. <input type="checkbox"/> REJ.	Cutting burr	Max 0.025	Max 0.050	1 JUN 2010
<input checked="" type="checkbox"/> APP. <input type="checkbox"/> REJ.	D/S depth	0.459+/-0.030	0.459+/-0.050	1 JUN 2010

B. Layout CHANGE ITEM			
Approve Or Rejected	ITEM	DESCRIPTION	Date
<input checked="" type="checkbox"/> APP. <input type="checkbox"/> REJ.	Change rail marking	As attached see	1 JUN 2010
<input checked="" type="checkbox"/> APP. <input type="checkbox"/> REJ.	Change H/E design	As attached see	1 JUN 2010

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<input checked="" type="checkbox"/> <b>APP.</b>	Change plating design	As attached see	1 JUN 2010
<input type="checkbox"/> <b>REJ.</b>			

SUPPLIER AUTHORIZED ENGINEERING APPROVAL		
Name(PRINT): YaoWen	ENGINEERING SIGNATURE Yaowen	DATE: 1 JUN 2010
R&D ENGINEERING SIGNATURE:		
Name(PRINT): Shiouling_Yeh	ENGINEERING SIGNATURE Shiouling_Yeh	DATE: 2010/06/01

Plating Thickness		
PPF	PLATING THICKNESS (Ni)	
	PLATING THICKNESS (Pd)	
	PLATING THICKNESS (Au)	
	PLATING THICKNESS (Ag)	

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## DEVIATION ITEM 1

page : 02/04

Diagram Before Modification

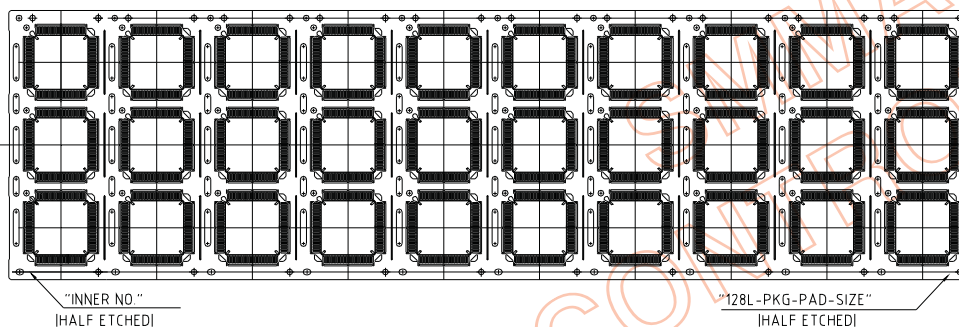
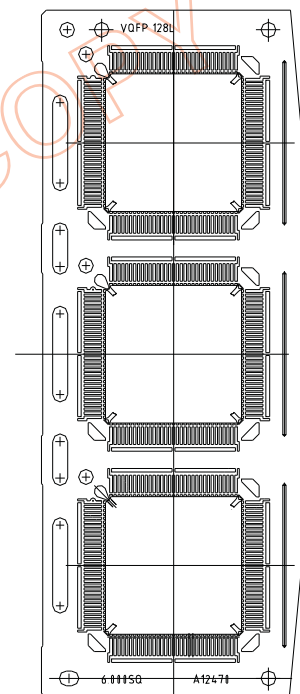


Diagram After Modification

1. TOP rail marking: VQFP128L
2. Bottom rail marking: 6.000SQ /A12470
3. For every unit.



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REV. C



## DEVIATION ITEM 1

page : 03/04

Diagram Before Modification

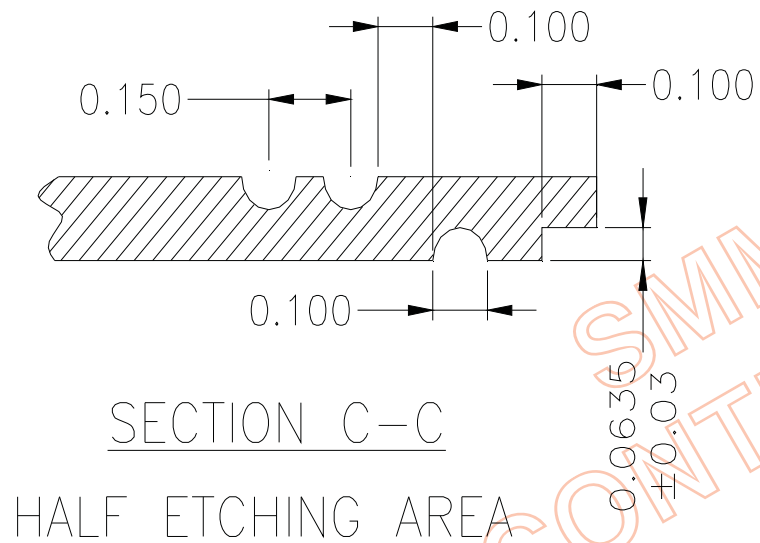
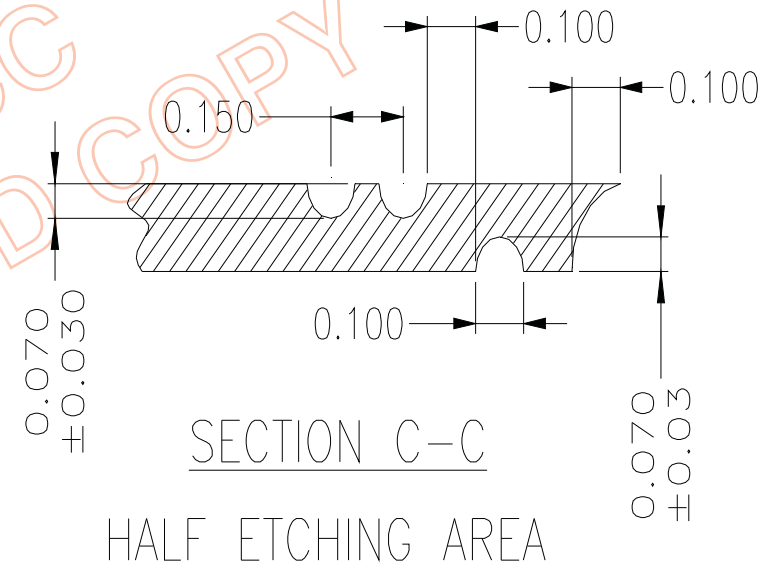


Diagram After Modification



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REV. C



# DEVIATION ITEM 1

Diagram Before Modification

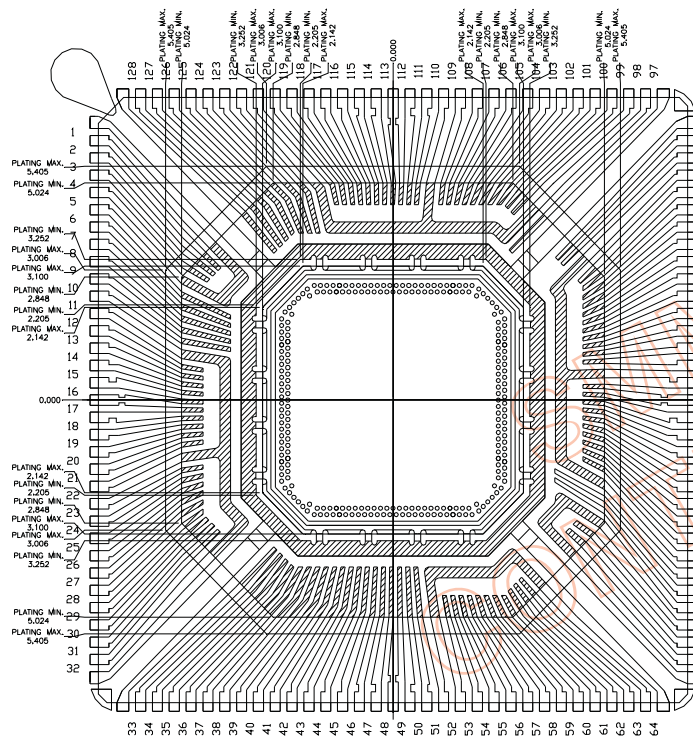
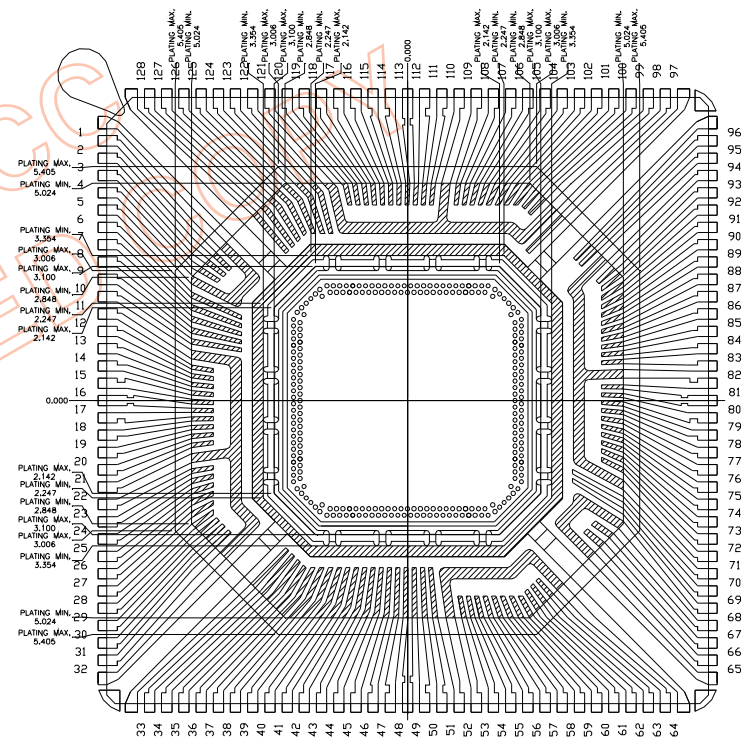


Diagram After Modification



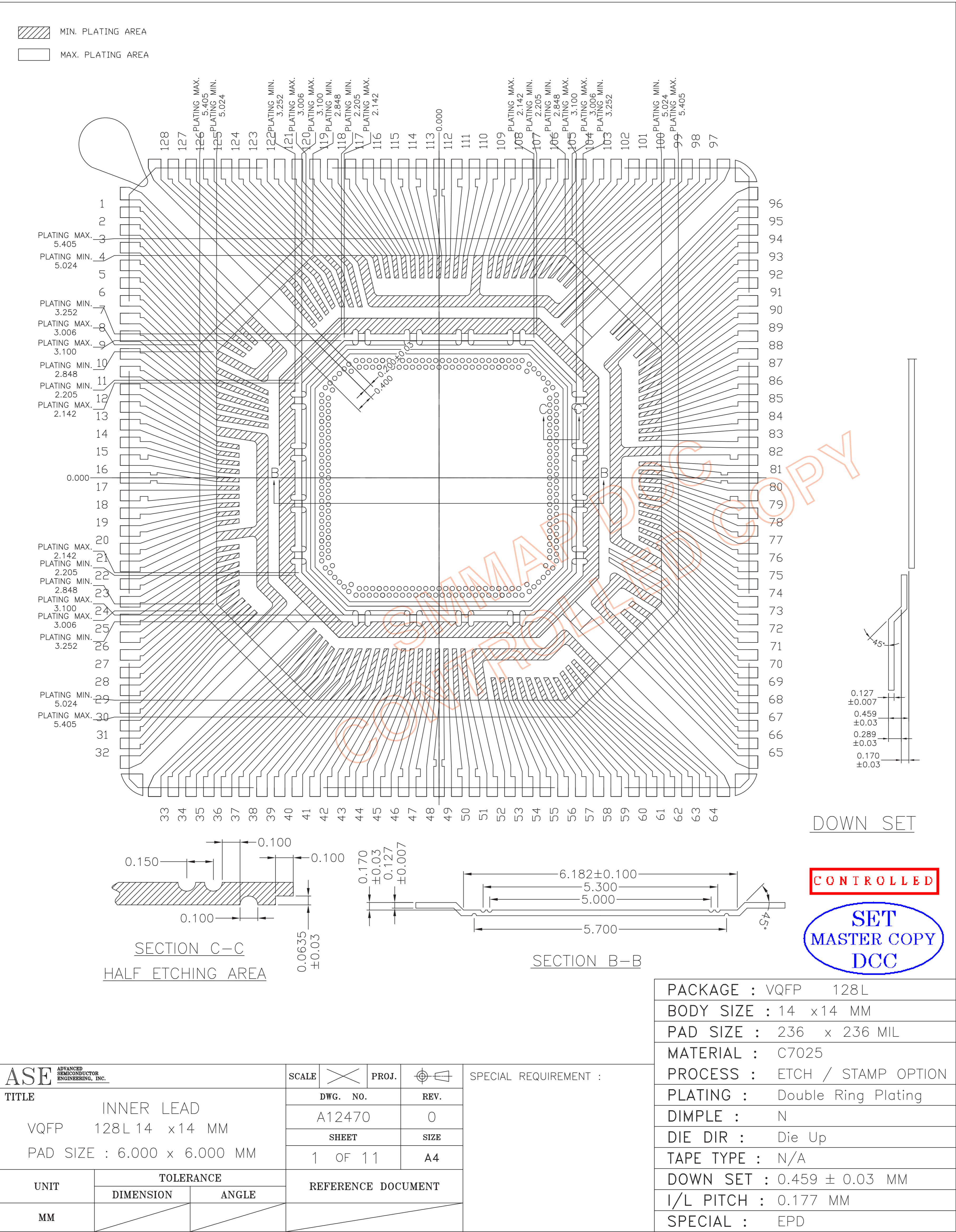
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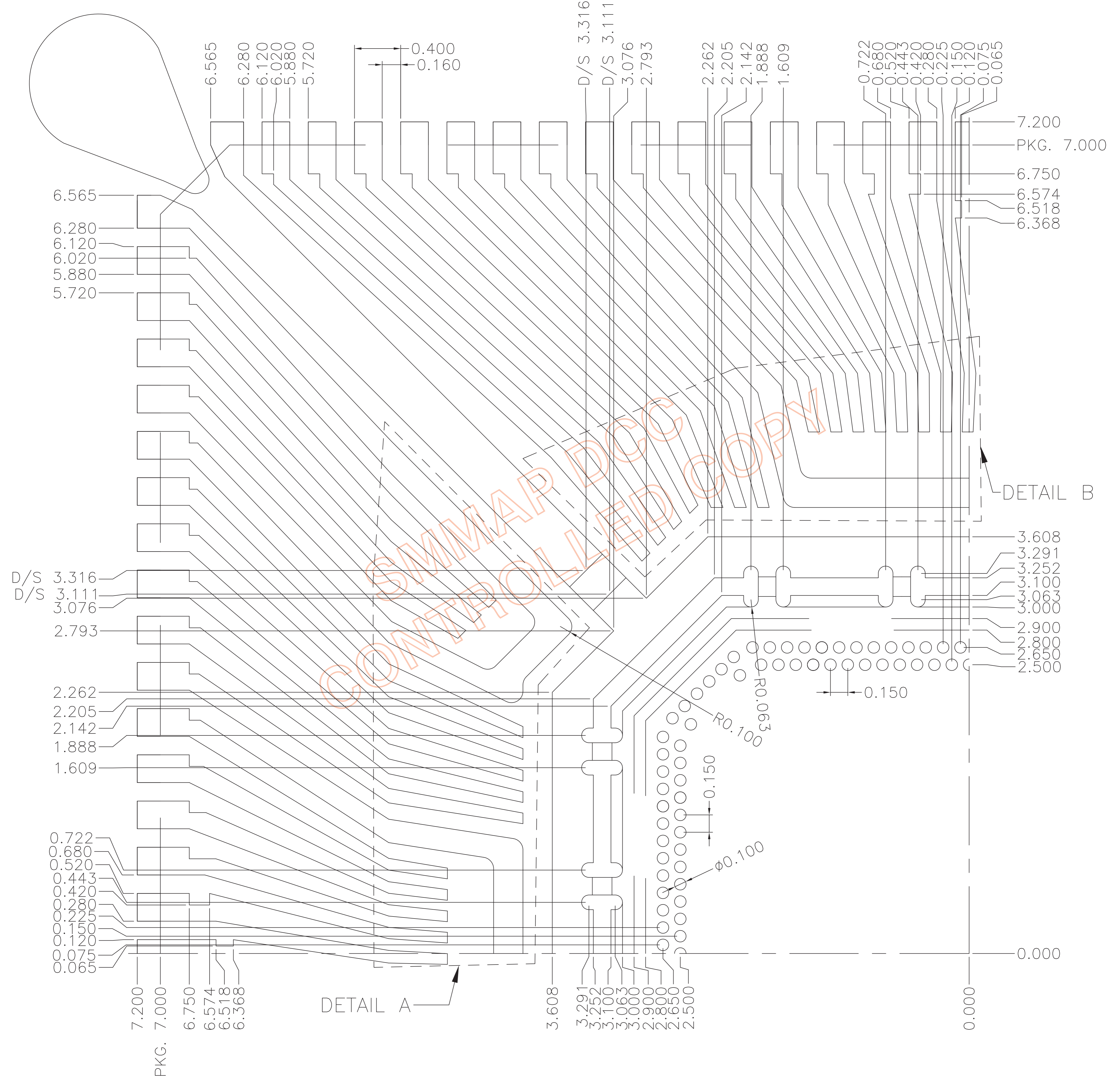
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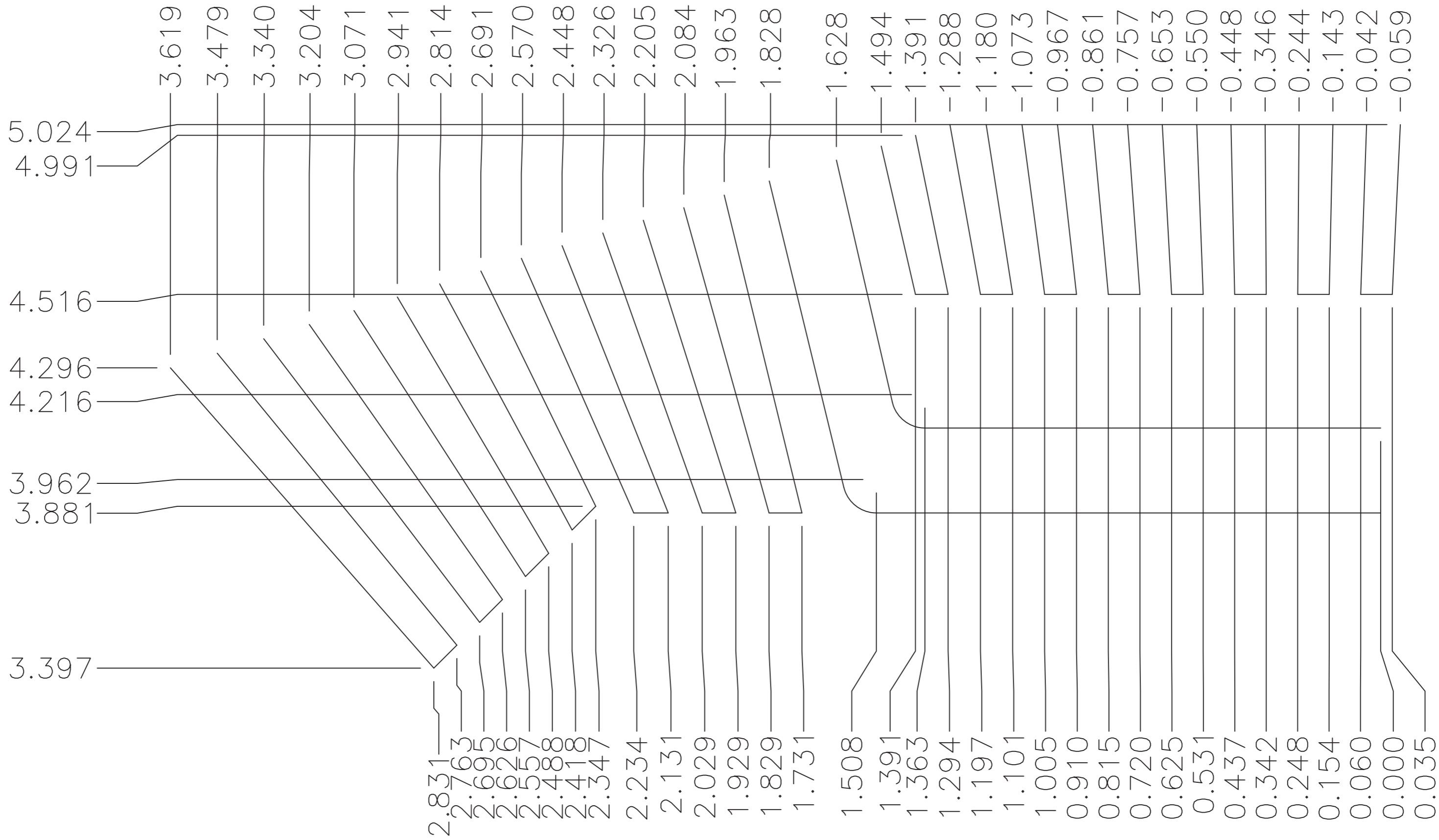


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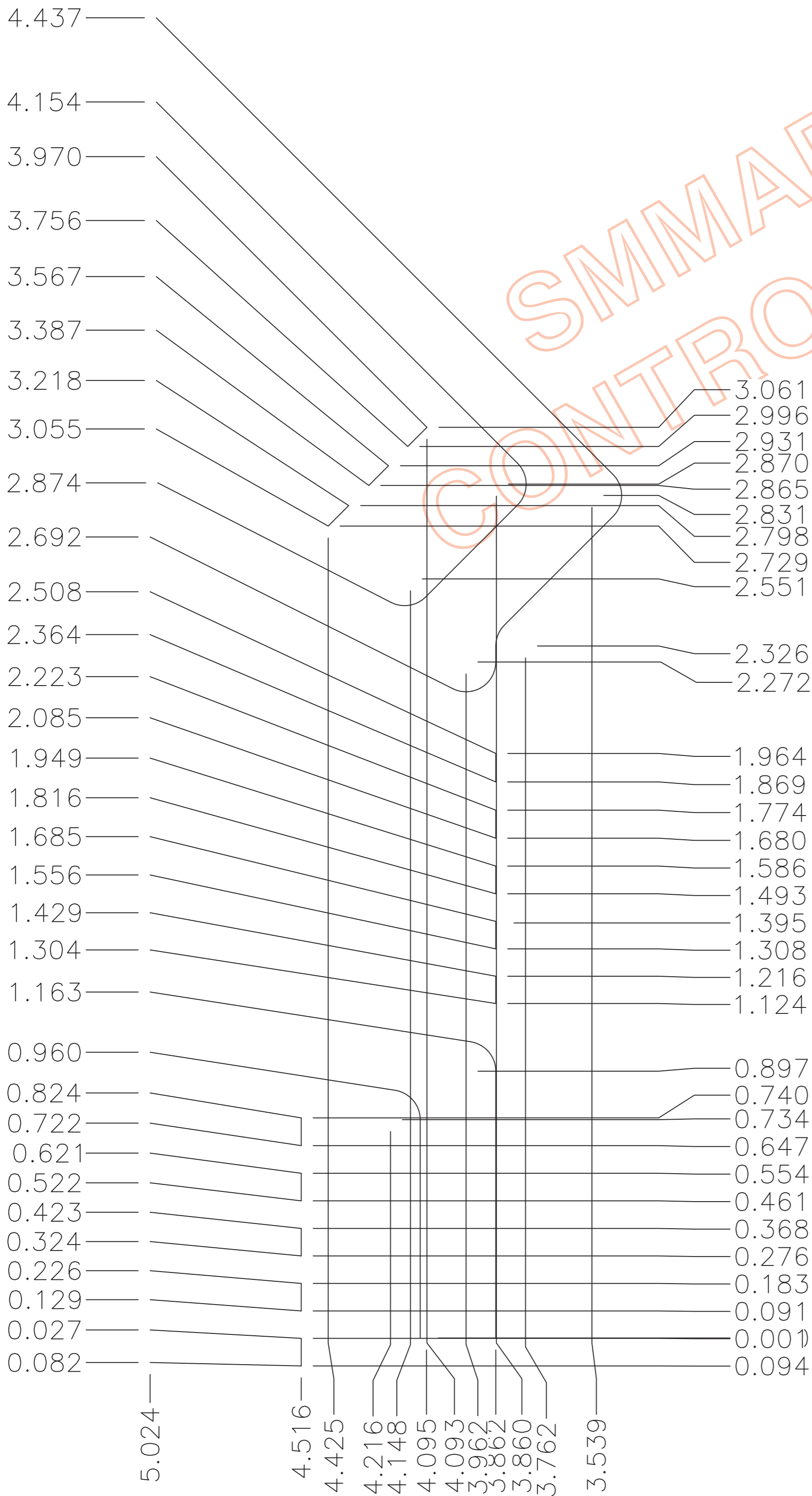
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		A12470	0
		SHEET	
		2 OF 11	
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DATE			
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DETAIL B

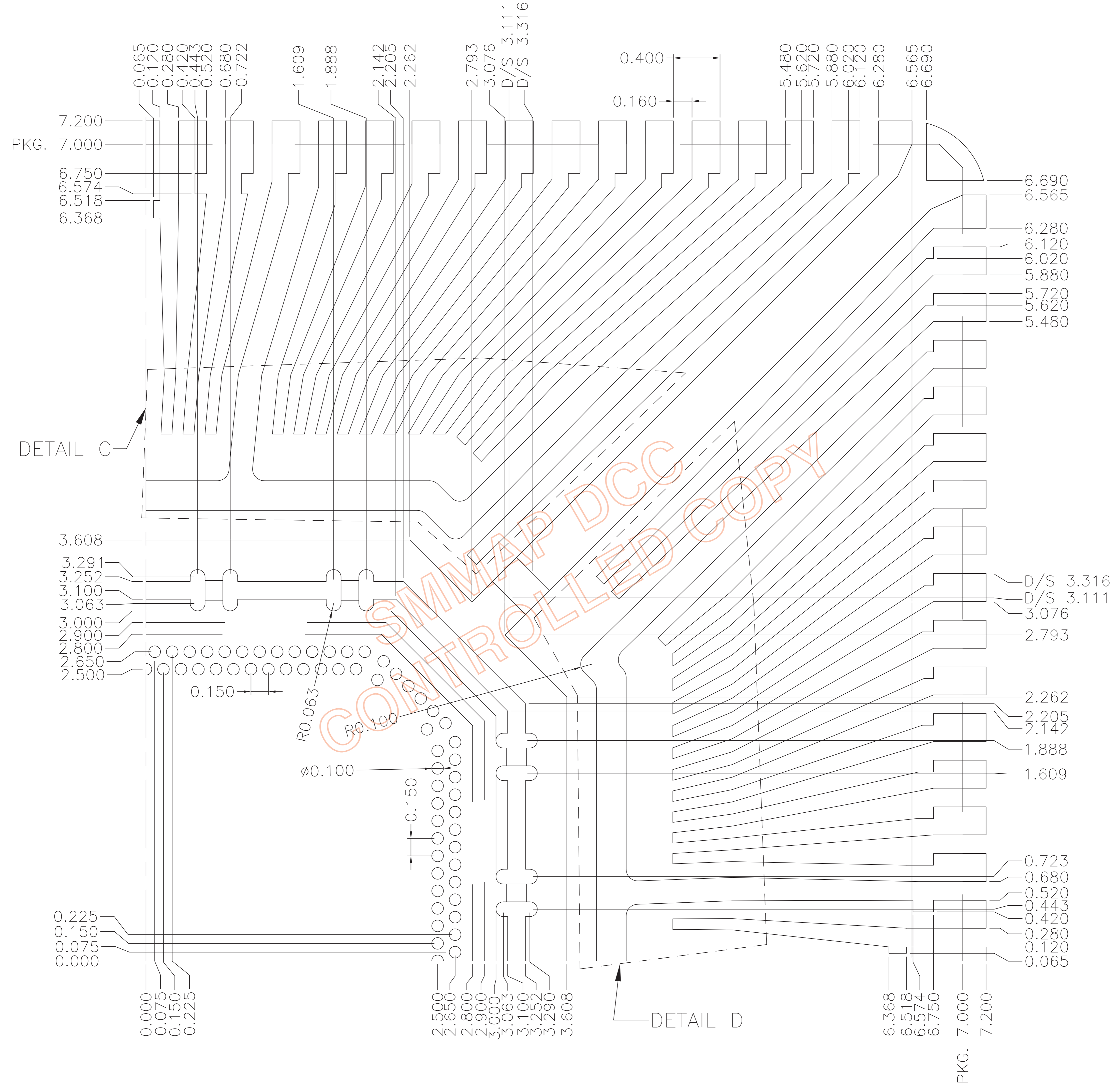


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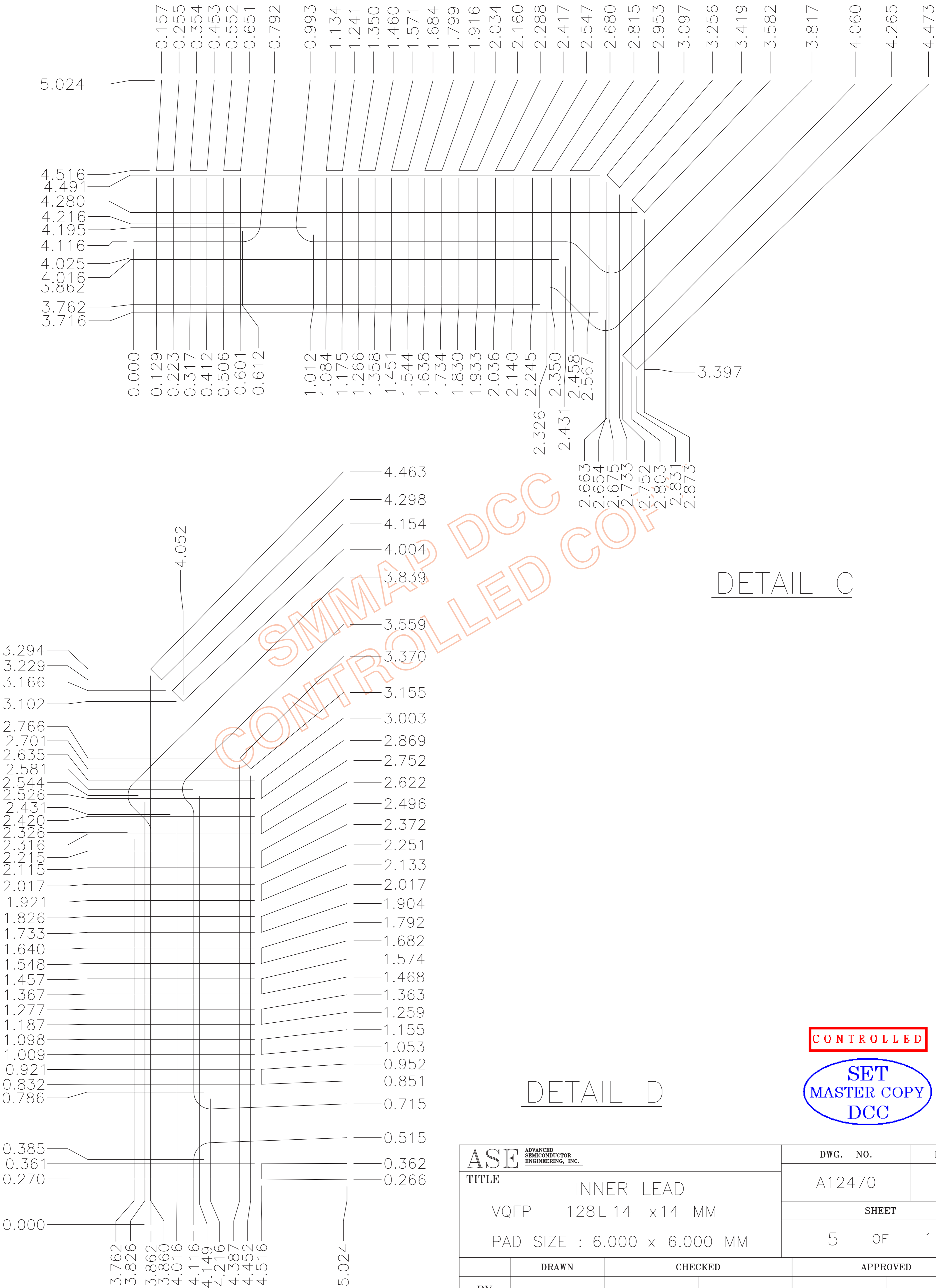


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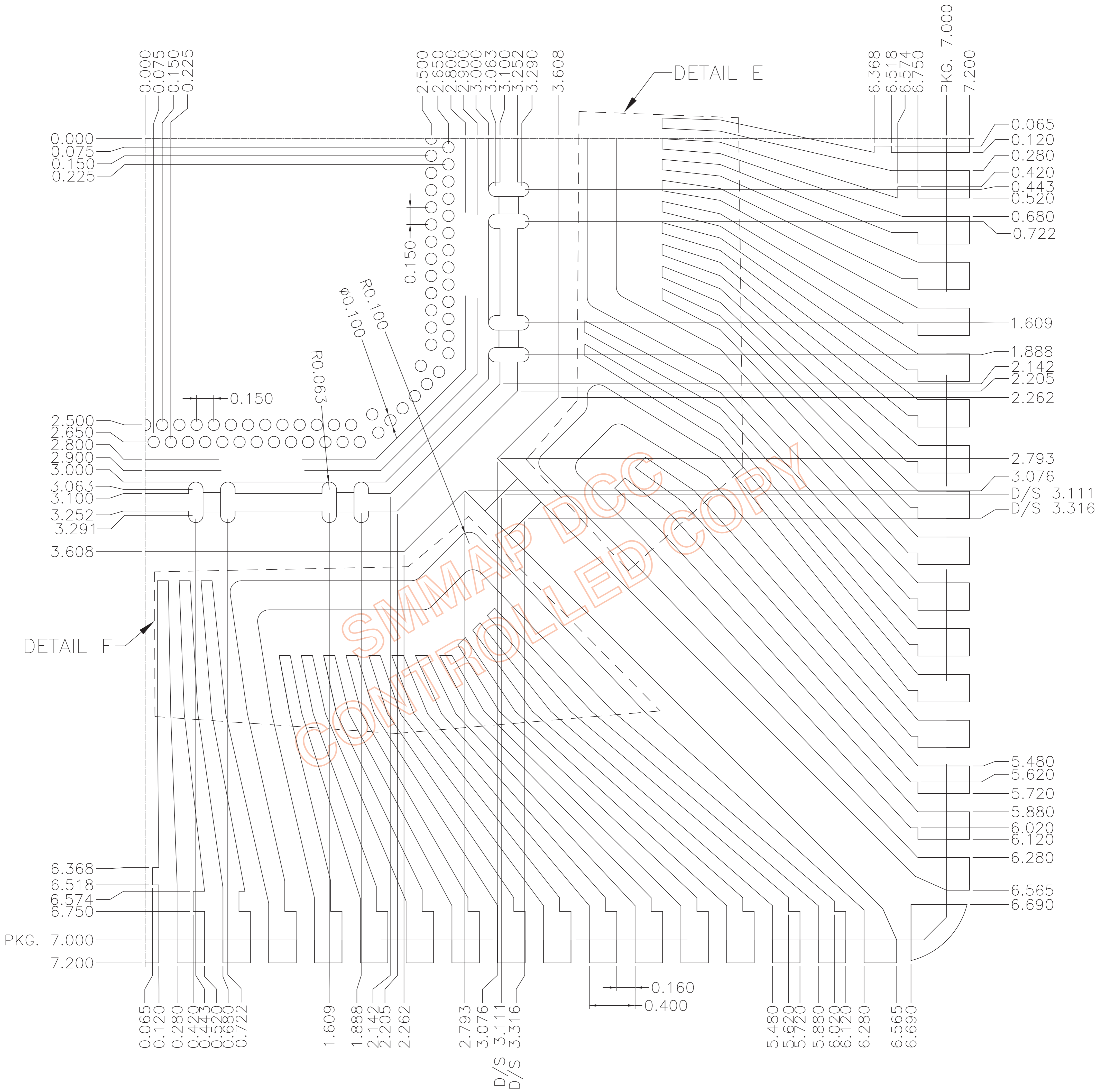
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VQFP 128L 14 x14 MM			5	OF 11
PAD SIZE : 6.000 x 6.000 MM				
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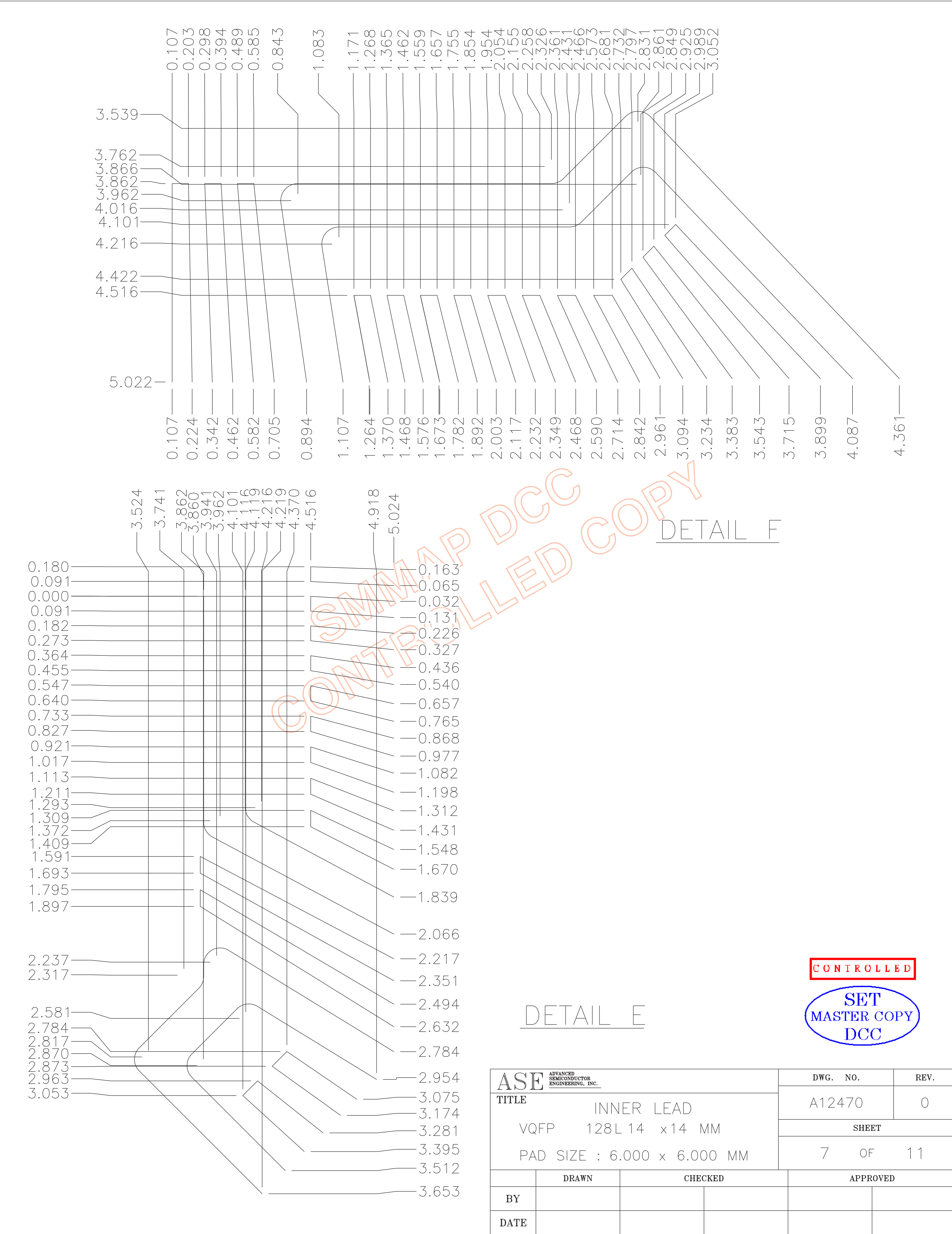


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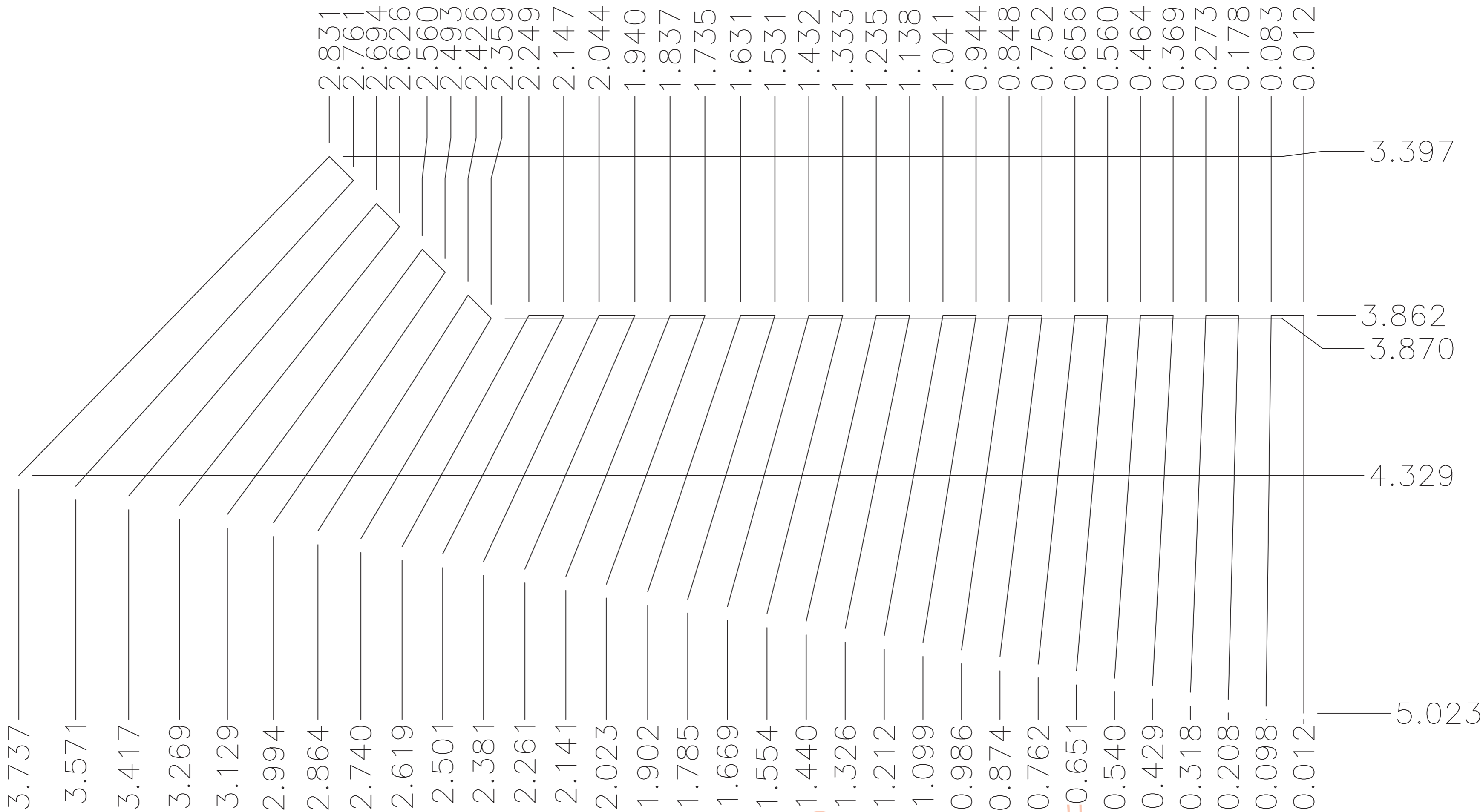
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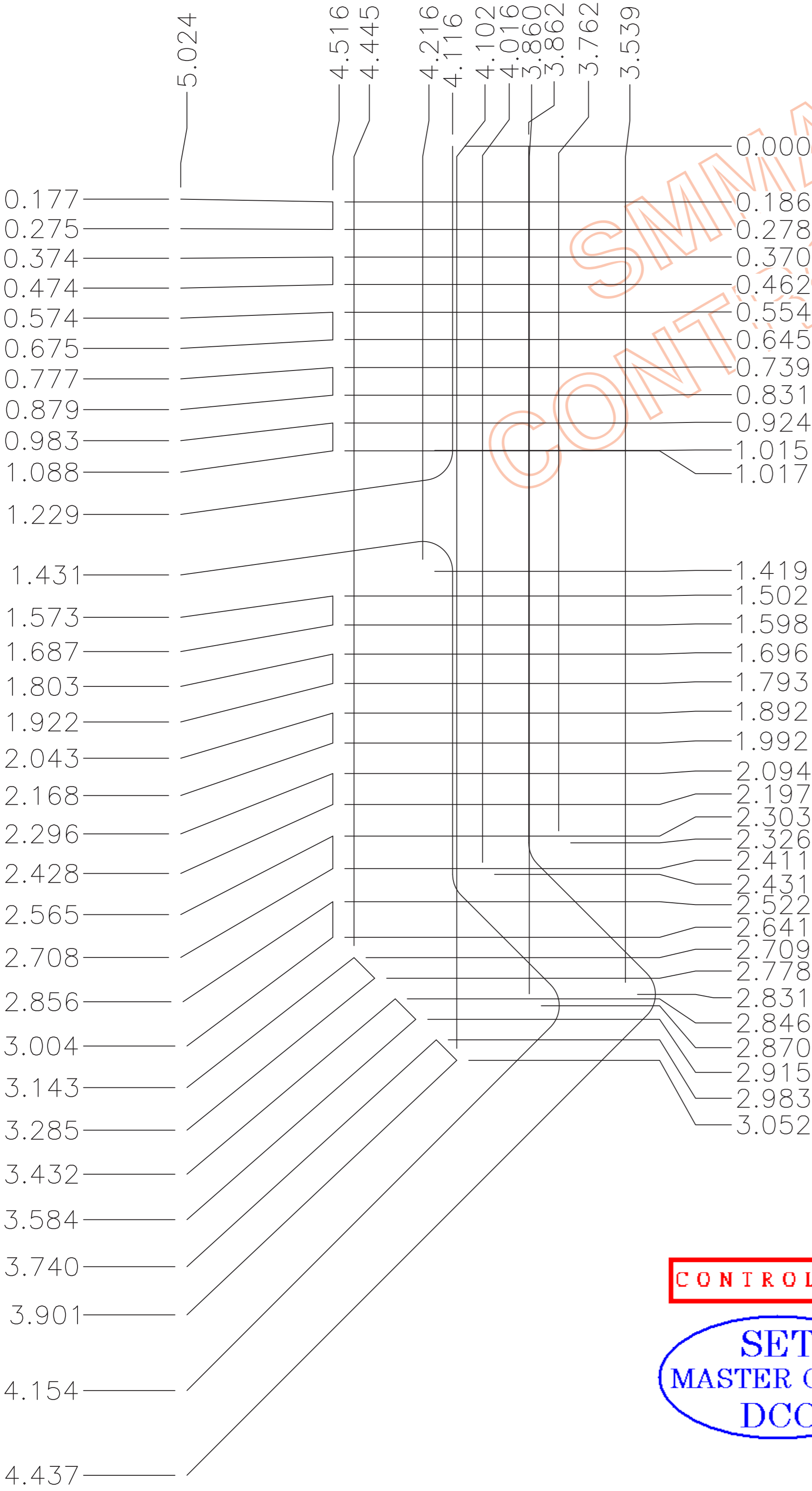
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DETAIL G



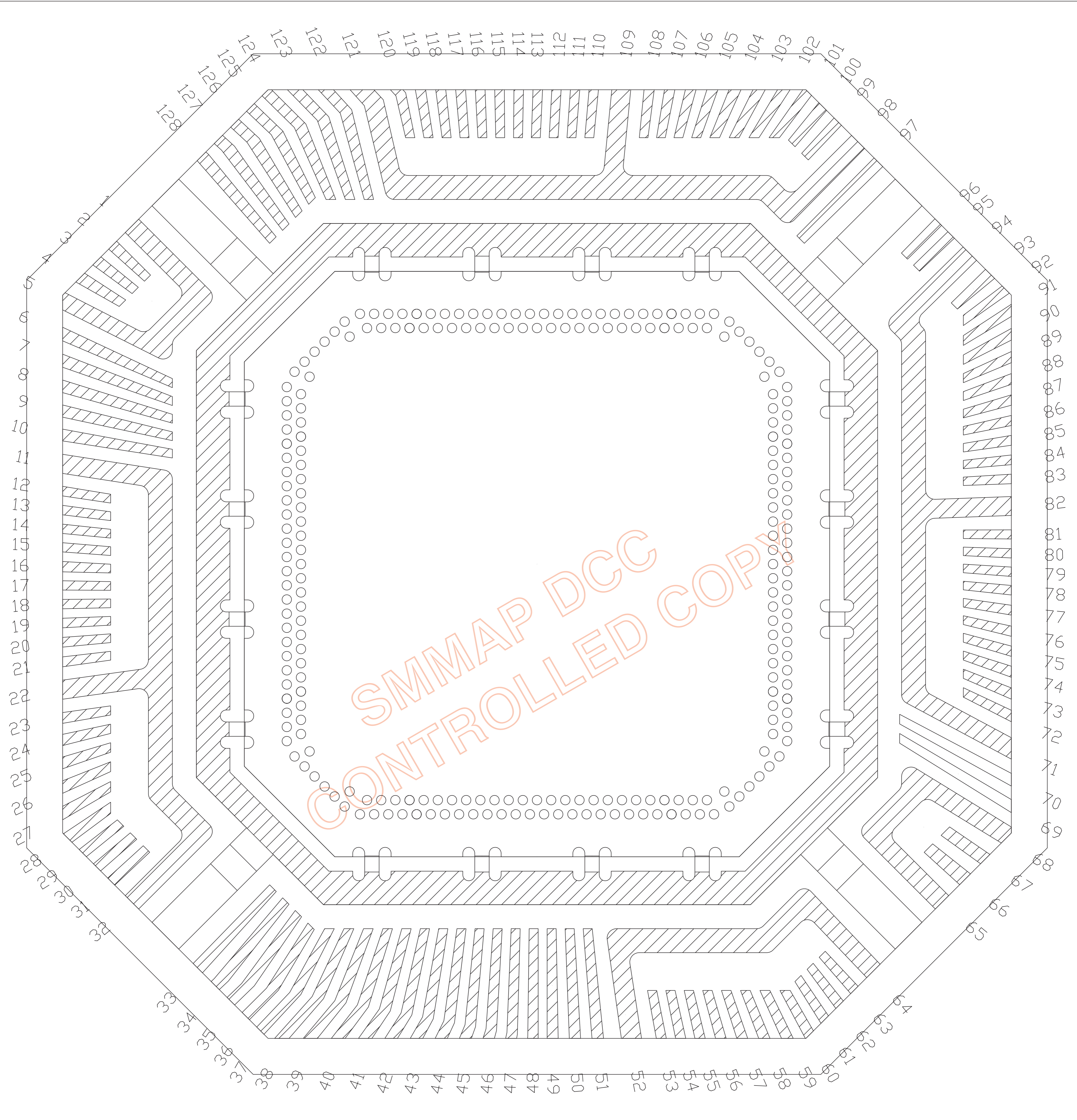
DETAIL H

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## REVISION HISTORY :

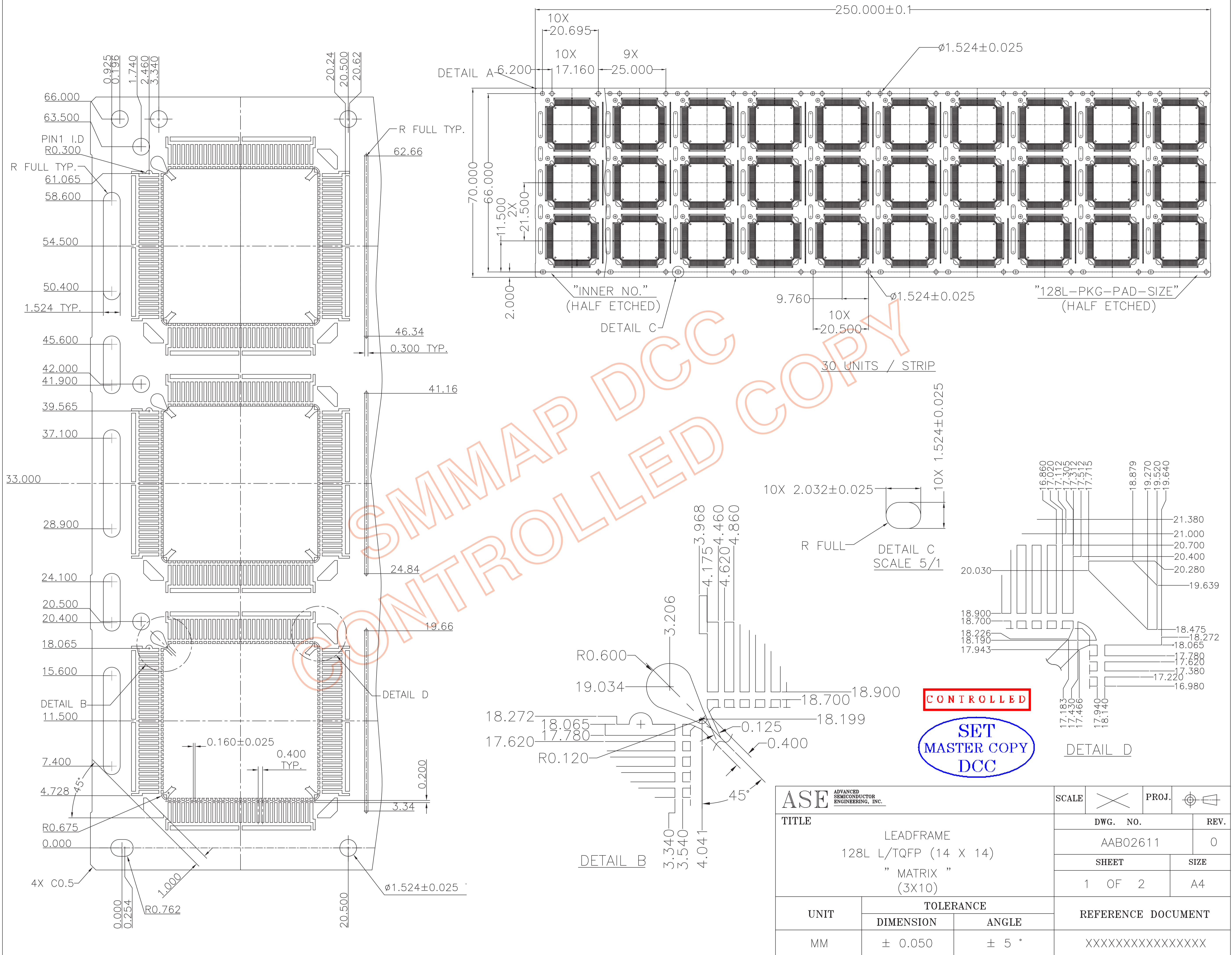
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DATE						

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ASE ADVANCED SEMICONDUCTOR ENGINEERING, INC.			SCALE		PROJ.	
TITLE  LEADFRAME  128L L/TQFP (14 X 14)  ” MATRIX ”  (3X10)			DWG. NO.		REV.	
			AAB02611		0	
			SHEET		SIZE	
			1 OF 2		A4	
UNIT	TOLERANCE		REFERENCE DOCUMENT			
	DIMENSION	ANGLE				
MM	± 0.050	± 5 °	XXXXXXXXXXXXXXXXXXXX			

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